## ISEM

WDFNW10 2.5x1.0, 0.5P CASE 515AH **ISSUE B** 

NDTES Α PIN DNE -В 2. 1.3 AЗ З. TOP VIEW PLATED SURFACE 4. DETAIL B SECTION C-C 8X 5. // 0.10 C C 0-0 SEATING C-PLANE NOTE 4 ΓĊΙ SIDE VIEW L3 L3 -2X b2 \_\_\_\_\_L ALTERNATE CONSTRUCTION 8X b e ⊕ 0.10 C A B
0.05 C
□ DETAIL A NOTE 3 BOTTOM VIEW

EXPOSED COPPER 2X 0.45--A1 A1 PACKAGE 1.60 -L PLATED 8X0.25 -0.50 PITCH PLATED SURFACE SURFACE ALTERNATE CONSTRUCTION RECOMMENDED MOUNTING FOOTPRINT

DETAIL B

DATE 03 AUG 2020

- 1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 2009.
- CONTROLLING DIMENSION: MILLIMETERS
- DIMENSION & APPLIES TO PLATED TERMINALS AND IS MEASURED BETWEEN 0.15 AND 0.30MM FROM THE TERMINAL TIP.
- COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
- THIS DEVICE CONTAINS WETTABLE FLANK DESIGN FEATURES TO AID IN FILLET FORMATION ON THE LEADS DURING MOUNTING.

	MILLIMETERS		
DIM	MIN.	NDM.	MAX.
Α	0.70	0.75	0.80
A1	0.00		0.05
A3	0.20 REF		
A4	0.10		
b	0.15	0.20	0.25
b2	0.35	0.40	0.45
D	2.40	2.50	2.60
E	0.90	1.00	1.10
e	0.50 BSC		
L	0.30	0.35	0.40
L3			0.10

## GENERIC **MARKING DIAGRAM\***

## XXXM

XX = Specific Device Code М

= Date Code

\*This information is generic. Please refer to device data sheet for actual part marking. Pb–Free indicator, "G" or microdot "∎", may or may not be present. Some products may not follow the Generic Marking.

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For additional information on our Pb-Free strategy soldering details, please download the DN Semiconduc Soldering and Mounting Techniques Reference Manual SDLDERRM/D.